

ABSTRACT OF THE DISCLOSURE

In one embodiment, a method of forming a metallic electrode comprises depositing a metal layer over a surface (e.g., substrate) and thermally processing the metal layer to form a conductive metallized ceramic. The metal layer may be deposited

5 by sputtering and thermally processed by rapid thermal processing, for example.

Among other advantages, embodiments of the present invention allow for the formation of conductive metallized ceramics, such as titanium-nitride, without the use of relatively expensive deposition tools.